

## **AMENDMENTS TO THE CLAIMS**

**Claim 1 (Cancelled)**

**Claim 2 (Cancelled)**

**Claim 3 (Cancelled)**

**Claim 4 (Cancelled)**

**Claim 5 (Currently Amended)** A dry etching method comprising etching a metallic surface of copper, silver, gold, or an alloy containing as a main component at least one of these metals by plasma of an etching gas containing a gaseous nitrogen oxide, hydrogen sulfide and ammonia while being reacted with the plasma.

**Claim 6 (Cancelled)**

**Claim 7 (Cancelled)**

**Claim 8 (Currently Amended)** A dry etching method as claimed in Claim 5, wherein a mask material selected from the group consisting of titanium and a titanium alloy covers the metallic surface on etching.

**Claim 9 (New)** A dry etching method comprising etching a metallic surface of copper, silver, gold, or an alloy containing as a main component at least one of these metals by plasma of an etching gas containing a gaseous nitrogen oxide and ammonia while being reacted with the plasma, wherein a mask material selected from the group consisting of titanium and a titanium alloy covers the metallic surface on etching.

**Claim 10 (New)** A dry etching method as claimed in Claim 9, wherein the etching gas further contains hydrogen sulfide.